

Call for Papers

Practical applications of explainable artificial intelligence methods special session at 10th IEEE International Conference on Data Science and Advanced Analytics (DSAA 2023)
Thessaloniki, Greece, 9-13 October, 2023

<https://www.geist.re/praxai:start>

Important Dates:

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** Submission Deadline: **May 22, 2023**
** Notification of Acceptance: **July 17, 2023**
** Camera-Ready Versions Due: **August 7, 2023**
** Conference date: **October 9-13, 2023**

PRAXAI special session at [The 10th IEEE International Conference on Data Science and Advanced Analytics](#) (DSAA'2022). The special session is planned to Thessaloniki, Greece, 9-13 October, 2023

Objectives

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This special session focuses on bringing the research on Explainable Artificial Intelligence (XAI) to actual applications and tools that help to better integrate them as a must-have step in every AI pipeline. We welcome papers that showcase how XAI has been successfully applied in real-world AI-based tasks, helping domain experts understand the results of a model. Moreover, we also encourage the submission of novel techniques to augment and visualize the information contained in the model explanations. Furthermore, we expect a presentation of practical development tools that make it easier for AI practitioners to integrate XAI methods into their daily work.

Topics of interest

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We encourage receiving papers related to the following topics, which include but are not limited to:

- Industry 4.0/5.0 and XAI
- Model explanations verbalized in human-comprehensible natural language
- Explainable Reinforcement learning
- Explainable AI for Planning and Decision Making
- Automation and XAI
- Cybersecurity and XAI
- Medical XAI
- Evaluation and visualization of explanations
- Software tools for interpretable machine learning and data mining
- Knowledge-augmented explanations
- Human in the loop explanations
- Interactive explanations
- Visualization of model explanations for different types of data apart from language and images (tabular data, time series, graphs, etc.)
- XAI software development and its integration into popular ML/DL libraries
- Fairness and XAI
- Ethics and XAI
- Trust in XAI systems
- XAI in real-world applications: case studies and success stories

Submission

The length of each paper submitted to the Research and Application tracks should be no more than 10 pages, whereas the maximum number of pages is 2 for each abstract submitted to the Poster and Journal track. Both types of papers should be formatted following the standard 2-column U.S. letter style of IEEE Conference template. See the IEEE Proceedings Author Guidelines: http://www.ieee.org/conferences_events/conferences/publishing/templates.html, for further information and instructions.

All submissions will be double-blind reviewed by the Program Committee on the basis of technical quality, relevance to the scope of the conference, originality, significance, and clarity. The names and affiliations of authors must not appear in the submissions, and bibliographic references must be adjusted to preserve author anonymity. Submissions failing to comply with paper formatting and authors anonymity will be rejected without reviews.

Authors are also encouraged to submit supplementary materials, i.e., providing the source code and data through a GitHub-like public repository to support the reproducibility of their research results.

Electronic submission site: <https://easychair.org/my/conference?conf=dsaa2023>

Organizing committee

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Program committee (tentative)

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We look forward to seeing you at the PRAXAI Special Session at DSAA'2023!

Sincerely,

Szymon Bobek, Victor Rodriguez-Fernandez, Przemysław Biecek, Grzegorz J. Nalepa